

In the Specification:

Please modify the Table included on page 10 of the Specification as follows:

	Title of Application	First Named Inventor
6,501,161	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
09/687,487	Clamp and Heat Block Assembly for Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley
09/687,495	Semiconductor Package	Sean Timothy Crowley
09/687,531	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
09/687,530	Stackable Semiconductor Package and Method for Manufacturing Same	Jun Young Yang
09/687,126	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
6,555,899	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung